SEMICONDUCTOR TOSHIBA

TECHNICAL DATA

TOSHIBA GATE TURN-OFF THYRISTOR

SGR3000EX26

REVERSE CONDUCTING TYPE

TENTATIVE DATA (SGR3000EX26)

INVERTER APPLICATION

Repetitive Peak Off-State Voltage: VDRM=2500V (Note. 1)

R.M.S On-State Current : $I_{T,(RMS)} = 1400A (Tf = 77^{\circ}C)$

R.M.S Reverse Current : $I_{R,(RMS)} = 1000A (Tf = 77^{\circ}C)$

: ITGOM = 3000A Peak Turn-Off Current

Critical Rate of Rise of On-State Current

: $di/dt = 500A/\mu s$

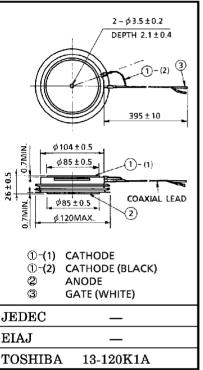
Critical Rate of Rise of Off-State Current

: $dv/dt = 1000V/\mu s$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT		
Repetitive Peak Off-State Voltage (Note 1)	$v_{ m DRM}$	2500	V		
Peak Turn-Off Current (Note 2)	I_{TGQM}	3000	Α		
R.M.S On-State Current (Note 3)	I _{T (RMS)}	1400	Α		
R.M.S Reverse Current (Note 3)	I _{R (RMS)}	1000	Α		
Peak One Cycle Surge On-State Current (non repetitive, 10ms-width half sine waveform)	I _{TSM}	16000 A			
Peak One Cycle Surge Reverse Current (non repetitive, 10ms-width half sine waveform)	I _{RSM}	16000 A			
Critical Rate of Rise of On-State Current (Note 4)	di / dt	500	A/μs		
Peak Forward Gate Current	I_{FGM}	100	A		
Average Forward Gate Power Dissipation	P _{FG} (AV)) 50 V			
Average Reverse Gate Power Dissipation	P _{RG (AV)}	230	W		
Peak Reverse Gate Power Dissipation	P_{RGM}	30	kW		
R.M.S Gate Current (Note 5)	I _G (RMS)	42	Α		
Peak Reverse Gate Voltage (at Static)	V_{RGM}	16	V		
Operating Junction Temperature Range	T_{j}	-40~125	°C		
Storage Temperature Range	$T_{ m stg}$	-40~150 °			
Mounting Force	_	39.2±4.9	kN		

Unit in mm



Weight: 1700g

Note 1 $V_{GK} \leq -2V$

Note 2 VDM=2500V, CS=5 μ F, RS=5 Ω , diGQ/dt=50A/ μ s, LS \leq 0.2 μ H, VDSP \leq 850V Note 3 50Hz Half Sine Waveform at Tf=77°C

Note 4 $V_D=1/2V_{DRM}$, $I_{TM}=3000A$, $I_{GM}=25A$

Note 5 Ambient Temperature of coaxial gate-cathode lead=90°C

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TOSHIBA CORPORATION

SEMICONDUCTOR **TOSHIBA**

TECHNICAL DATA

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(SGR3000EX26)

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current	$I_{ m DRM}$	$V_{ m DRM}$ =RATED, $V_{ m GK}$ = -2V, $T_{ m j}$ =125°C		_	_	100	mA
Repetitive Peak Reverse Gate Current	I_{RGM}	$V_{\rm RGM}$ =18V, $T_{\rm j}$ =25°C		_	_	250	mA
Peak On-State Voltage	${ m V_{TM}}$	$I_{TM} = 3000A, T$	$\Gamma_{\rm j} = 125^{\circ}{ m C}$	_	_	3.5	V
Peak Reverse Voltage	v_{RM}	I _{RM} =3000A, T _j =125°C		_	_	3.0	V
Gate Trigger Voltage	v_{GT}	V 94V	$T_j = -40^{\circ}C$ $T_i = 25^{\circ}C$	_		1.20	v
Cata Thioman Cumant	Tom	$V_D = 24V$, $R_L = 0.1\Omega$	$T_j = -40^{\circ}C$	_ _	_	1.20 —	
Gate Trigger Current	IGT		$T_j = 25$ °C	_	_	4.0	A
Turn-On Delay Time	$^{ m t_d}$	$V_{D} = 1/2V_{DRM},$ $di/dt = 400A/\mu s,$		_	_	3	
Turn-On Time	t_{gt}	I_{GM} =25A, di_G/dt =10A/ μ s, T_j =25°C	_	_	10	μs	
Critical Rate of Rise of Off-State Voltage	dv / dt	$V_{ m DRM}$ =2/3RATED, $T_{ m j}$ =125°C, $V_{ m GK}$ =-15V		1000	_	_	V/μs
Storage Time	t_{S}	$V_{\rm DM}$ = 2500V, $I_{\rm TGQ}$ = 3000A,		_	_	22	
Gate Turn-Off Time	$ m t_{gq}$	$V_D = 1/2V_{DRM}$	_	_	24	μ s	
Gate Turn-Off Current	${ m I}_{ m GQ}$	$egin{array}{l} { m di}_{ m GQ} / { m dt} = & 50{ m A} / \mu { m s}, \ { m C}_{ m S} = & 5 \mu { m F}, \ { m R}_{ m S} = & 5 \Omega, \ { m T}_{ m j} = & 125 { m ^{\circ}C}, \ { m L}_{ m S} \leq & 0.2 \mu { m H} \end{array}$		_	700	_	Α
Tail Time	$t_{ m tail}$			$(V_D =$	500V)	80	μs
Commutating Critical Rate of Rise of Off-State Voltage	dv / dt (c)	$\begin{split} &I_{RM}\!=\!2500\text{A},\\ &\text{dig/dt}\!=\!300\text{A}/\mu\text{s},\\ &V_{D}\!=\!1000\text{V},V_{DM}\!=\!2000\text{V},\\ &C_{S}\!=\!3\mu\text{F},V_{GK}\!=\!-15\text{V},\\ &T_{j}\!=\!125^{\circ}\text{C} \end{split}$		250	_	_	V/μs
Reverse Recovery Charge	Q_{rr}	I_{RM} =2000A, V_D =500V, di_R/dt =100A/ μ s, T_j =125°C (no snubber circuit)		_	_	1800	μ C
Peak Reverse Recovery Current	I_{rr}			_	_	400	A
Thermal Resistance (Junction to	Daga	DC GTO Side		_	_	0.016	°C/W
Fin)	$ m R_{th~(j-f)}$	Dio	de Side	_	_	0.025	C / W

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